

Heat Transfer Society of Japan and IIS Univ. Tokyo

2nd International Forum on Heat Transfer (IFHT2008)

September 17th (Wed) – 19th (Fri), 2008, Tokyo, Japan

Scope

The International Forum on Heat Transfer (IFHT) is held by the Heat Transfer Society of Japan (HTSJ), which is the world-largest and most active heat transfer society, to create new trends by gathering the researchers from all over the world. The first IFHT was held at 2004 in Kyoto with approximately 150 presentations and 200 participants, where the collaboration of nano-, micro- and bio-technologies with heat transfer were selected as main theme.

The main theme of 2nd IFHT is planned as the collaboration of energy and environmental technologies with heat transfer, and keynote presentations from the world-famous researchers are scheduled. The general presentations are also available in all area of heat and mass transfer. The organizing committee invites participants to made presentations.

Date and Location

September 17th (Wed) – 19th (Fri), 2008, IIS Univ. Tokyo

Key Note Speakers (Tentative list)

Samuel Graham (Georgia Institute of Technology, USA),
S. H. Winoto (National Univ. Singapore, Singapore),
Yannick DeWild (National Center for Scientific Research, France),
Xing Zhang (Tsinghua Univ., China), “ “
Shuichiro Hirai (Tokyo Institute of Technology, Japan),
Shu Takagi (Univ. Tokyo, Japan),

Cooperating Society

Organizing Committee

I. Satoh (Chair, Tokyo Inst. Tech., Japan)

Ishizuka, M. (Chair, Toyama Pref. Univ., Japan)
Shirakashi, R. (Univ. Tokyo, Japan)
Miyazaki, K.(Kyushu Inst. Tech., Japan)
Munakata, T.(AIST, Japan)
Nakabe,K. (Kyoto Univ., Japan)
Nishino, K. (Yokohama National Univ., Japan)
Ohara, T.(Tohoku Univ., Japan)

Nakabeppu, O.(Meiji Univ., Japan)
Tanahashi, M.(Tokyo Inst. Tech., Japan)
Mimatsu, J.(Gifu Univ., Japan)
Murata, A(Tokyo Univ. A&T., Japan)
Nakagawa S.(Toyama Pref. Univ., Japan)
Ogawa, K.(Keio Univ., Japan)
Shibahara,M.(Osaka Univ., Japan)

Shikazono, N.(Univ. Tokyo, Japan)
Tada, Y.(Kanazawa Univ., Japan)
Yamada, J.(Shibaura Inst. Tech., Japan)
Yazawa, K.(Sony Corp., Japan)

Suzuki, O.(Hitachi Ltd., Japan)
Takata, Y.(kyushu Univ., Japan)
Yamada, M.(Hokkaido Univ., Japan)
Yokono, Y.(Toshiba Corp., Japan)

Executive Committee

Ishizuka, M. (Chair, Toyama Pref. Univ., Japan)
Nakabe, K. (Kyoto Univ., Japan)
Shirakashi, R. (Univ. Tokyo, Japan)
Tanahashi, M.(Tokyo Inst. Tech., Japan)

I. Satoh (Chair, Tokyo Inst. Tech., Japan)
Nakabeppu, O.(Meiji Univ., Japan)
Miyazaki, K.(Kyushu Inst. Tech., Japan)

Forum Organization

- Six keynote presentations from the cutting edge of various areas related to heat transfer, especially those from Energy and Environmental research areas.
- Approx. 150 general presentations by both poster and short oral presentation.
- Panel discussion

Deadlines

December 31, 2007	Deadline for short abstract
February 28, 2008	Notification of acceptance to authors
May 31, 2008	Deadline for camera-ready manuscript of extended abstract (Two to six pages in A4 format)
June 30, 2008	Deadline of registration

Forum Web Site : Under construction